





400V NPN HIGH VOLTAGE TRANSISTOR IN SOT89

Features

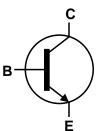
- BV_{CEO} > 400V
- I_C = 225mA Continuous Collector Current
- I_{CM} = 500mA Peak Pulse Current
- Excellent h_{FE} Characteristics up to 100mA
- Low saturation voltage V_{CE(sat)} < 200mV @ 20mA
- Complementary PNP Type: FCX558
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

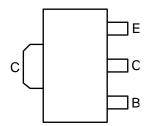
- Case: SOT89
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.055 grams (Approximate)







Equivalent Circuit



Top View Pin-Out

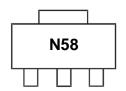
Ordering Information (Note 4)

| Product | Compliance | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|----------|------------|---------|--------------------|-----------------|-------------------|
| FCX458TA | AEC-Q101 | N58 | 7 | 12mm | 1,000 |

Notes:

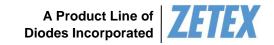
- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



N58 = Product Type Marking Code





Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|------------------------------|------------------|-------|------|
| Collector-Base Voltage | V _{CBO} | 400 | V |
| Collector-Emitter Voltage | V_{CEO} | 400 | V |
| Emitter-Base Voltage | V _{EBO} | 7 | V |
| Continuous Collector Current | Ic | 225 | mA |
| Peak Pulse Current | I _{CM} | 500 | mA |
| Base Current | I _B | 200 | mA |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|---|-------------|----------------|------|------|
| | (Note 5) | | 0.7 | W |
| Dower Dissipation | (Note 6) | | 1.0 | |
| Power Dissipation | (Note 7) | P _D | 1.5 | |
| | (Note 8) | | 2.0 | |
| | (Note 5) | $R_{	hetaJA}$ | 178 | °C/W |
| Thermal Decistores Lunction to Ambient Air | (Note 6) | | 125 | |
| Thermal Resistance, Junction to Ambient Air | (Note 7) | | 83 | |
| | (Note 8) | | 60 | |
| Thermal Resistance, Junction to Lead | (Note 9) | $R_{	hetaJL}$ | 22 | |
| Operating and Storage Temperature Range | T_J,T_STG | -65 to +150 | °C | |

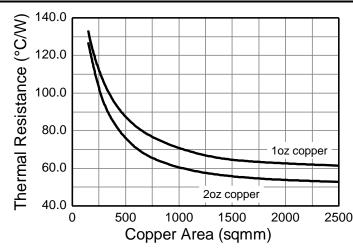
ESD Ratings (Note 10)

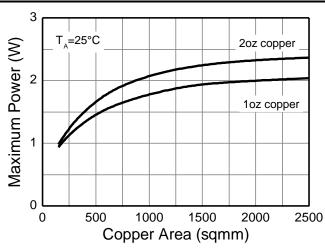
| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | С |

Notes:

- 5. For a device mounted with the exposed collector pad on minimum recommended pad layout (MRP) 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 6. Same as Note 5, except the device is mounted with the exposed collector pad on 15mm x 15mm 1oz copper.
- 7. Same as Note 5, except the device is mounted with the exposed collector pad on 25mm x 25mm 1oz copper.
- 8. Same as Note 5, except the device is mounted with the exposed collector pad on 50mm x 50mm 1oz copper.
- 9. Thermal resistance from junction to solder-point (on the exposed collector pad).
- 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

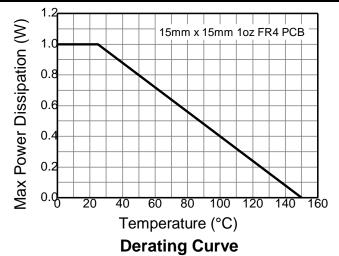
Thermal Characteristics and Derating Information

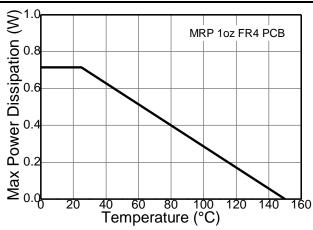




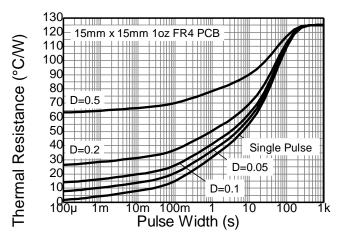


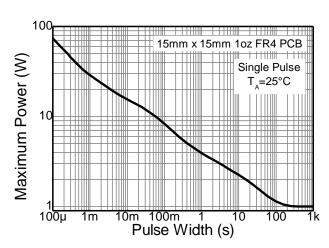
Thermal Characteristics and Derating Information (cont.)





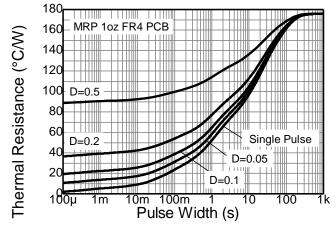
Derating Curve

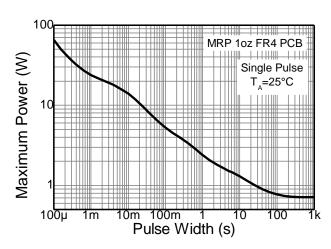




Transient Thermal Impedance

Pulse Power Dissipation

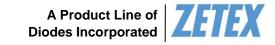




Transient Thermal Impedance

Pulse Power Dissipation





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|--|----------------------|------------------|------|------------|------|--|
| Collector-Base Breakdown Voltage | BV _{CBO} | 400 | _ | _ | V | I _C = 100μA |
| Collector-Emitter Breakdown Voltage (Note 11) | BV _{CEO} | 400 | _ | _ | V | I _C = 1mA |
| Emitter-Base Breakdown Voltage | BV _{EBO} | 7 | _ | _ | V | I _E = 100μA |
| Collector-Base Cutoff Current | I _{CBO} | _ | <1 | 100 | nA | V _{CB} = 320V |
| Collector Cutoff Current | I _{CES} | _ | <1 | 100 | nA | V _{CES} = 320V |
| Emitter Cutoff Current | I _{EBO} | _ | <1 | 100 | nA | V _{EB} = 5.6V |
| Collector-Emitter Saturation Voltage (Note 11) | V _{CE(sat)} | _ | _ | 200 500 | mV | $I_C = 20\text{mA}, I_B = 2\text{mA}$ $I_C = 50\text{mA}, I_B = 6\text{mA}$ |
| Base-Emitter Saturation Voltage (Note 11) | V _{BE(sat)} | _ | _ | 900 | mV | $I_C = 50\text{mA}, I_B = 5\text{mA}$ |
| Base-Emitter Turn-On Voltage (Note 11) | V _{BE(on)} | _ | _ | 900 | mV | I _C = 50mA, V _{CE} = 10V |
| DC Current Gain (Note 11) | h _{FE} | 100 100 15 | _ | 300 | _ | $I_C = 1$ mA, $V_{CE} = 10$ V $I_C = 5$ 0mA, $V_{CE} = 10$ V $I_C = 10$ 0mA, $V_{CE} = 10$ V |
| Transitional Frequency | f⊤ | 50 | _ | _ | MHz | $I_C = 10$ mA, $V_{CE} = 20$ V, $f = 20$ MHz |
| Output Capacitance | C _{obo} | _ | _ | 5 | pF | V _{CB} = 20V. f = 1MHz |
| Turn-On Time | t _{on} | _ | 135 | _ | ns | I _C =50mA, V _{CE} =100V, |
| Turn-Off Time | t _{off} | _ | 2260 | _ | ns | $I_{B1} = 5mA, I_{B2} = -10mA$ |

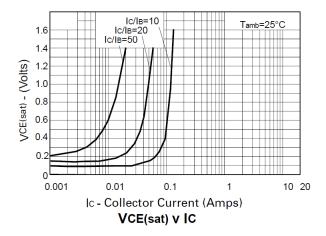
Note:

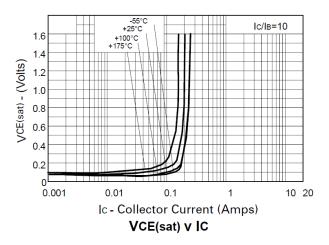
11. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%

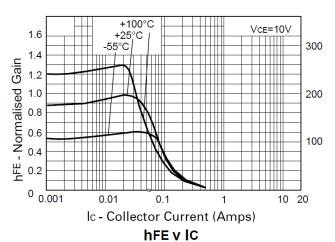


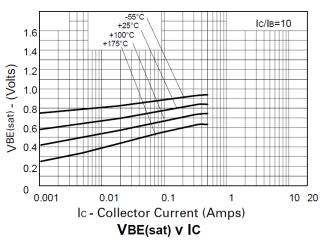


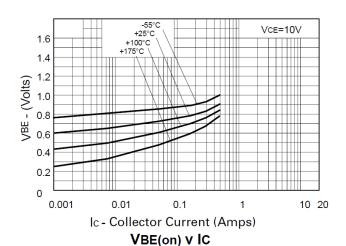
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)



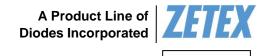






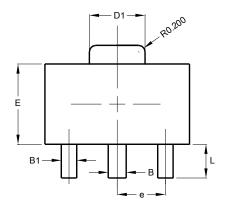


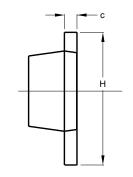


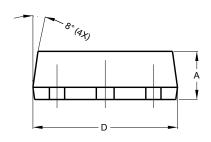


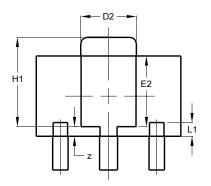
Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.





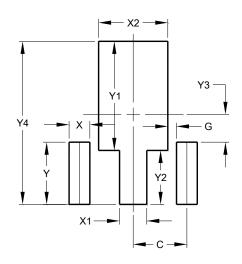




| SOT89 | | | | | |
|----------------------|-----------|------|-------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 1.40 | 1.60 | 1.50 | | |
| В | 0.50 | 0.62 | 0.56 | | |
| B1 | 0.42 | 0.54 | 0.48 | | |
| С | 0.35 | 0.43 | 0.38 | | |
| D | 4.40 | 4.60 | 4.50 | | |
| D1 | 1.62 | 1.83 | 1.733 | | |
| D2 | 1.61 | 1.81 | 1.71 | | |
| Е | 2.40 | 2.60 | 2.50 | | |
| E2 | 2.05 | 2.35 | 2.20 | | |
| е | 1 | 1 | 1.50 | | |
| Н | 3.95 | 4.25 | 4.10 | | |
| H1 | 2.63 | 2.93 | 2.78 | | |
| L | 0.90 | 1.20 | 1.05 | | |
| L1 | 0.427 REF | | | | |
| Z | 0.30 REF | | | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | value |
|--------------|---------|
| Dilliensions | (in mm) |
| С | 1.500 |
| G | 0.244 |
| Х | 0.580 |
| X1 | 0.760 |
| X2 | 1.933 |
| Υ | 1.730 |
| Y1 | 3.030 |
| Y2 | 1.500 |
| Y3 | 0.770 |
| Y4 | 4.530 |
| | |

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.





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